

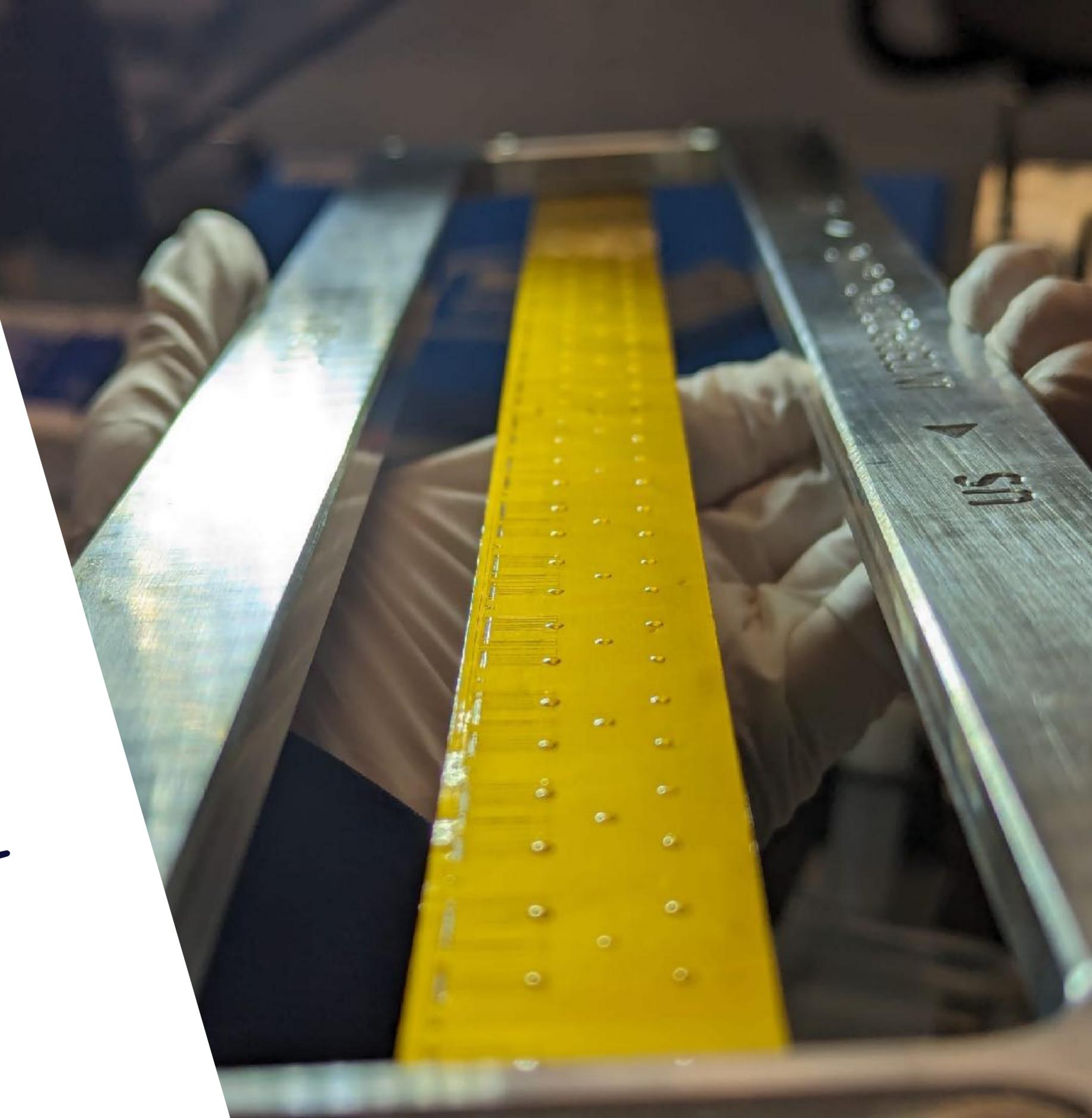
Ultra-lightweight  
outer pixel tracker for  
the Mu3e experiment

Ashley McDougall

On behalf of the Mu3e collaboration

Forum on Tracking Detector Mechanics

18.06.2025



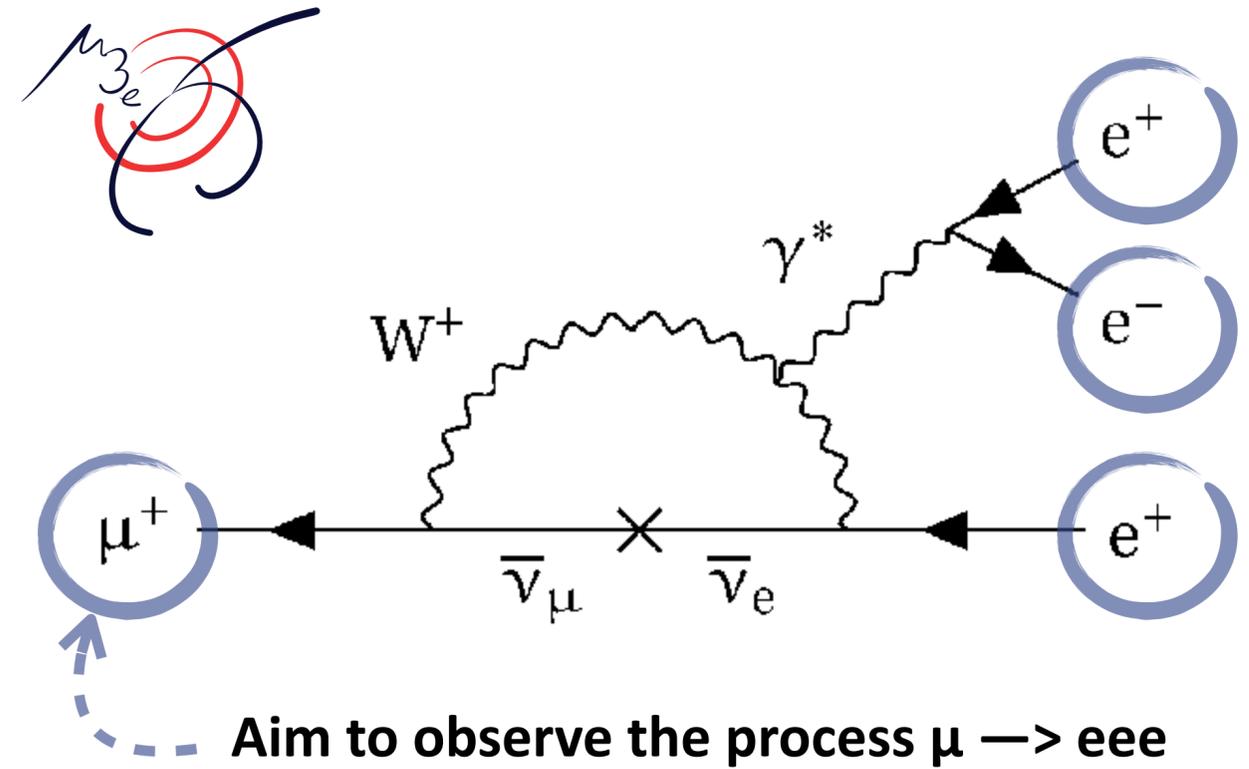
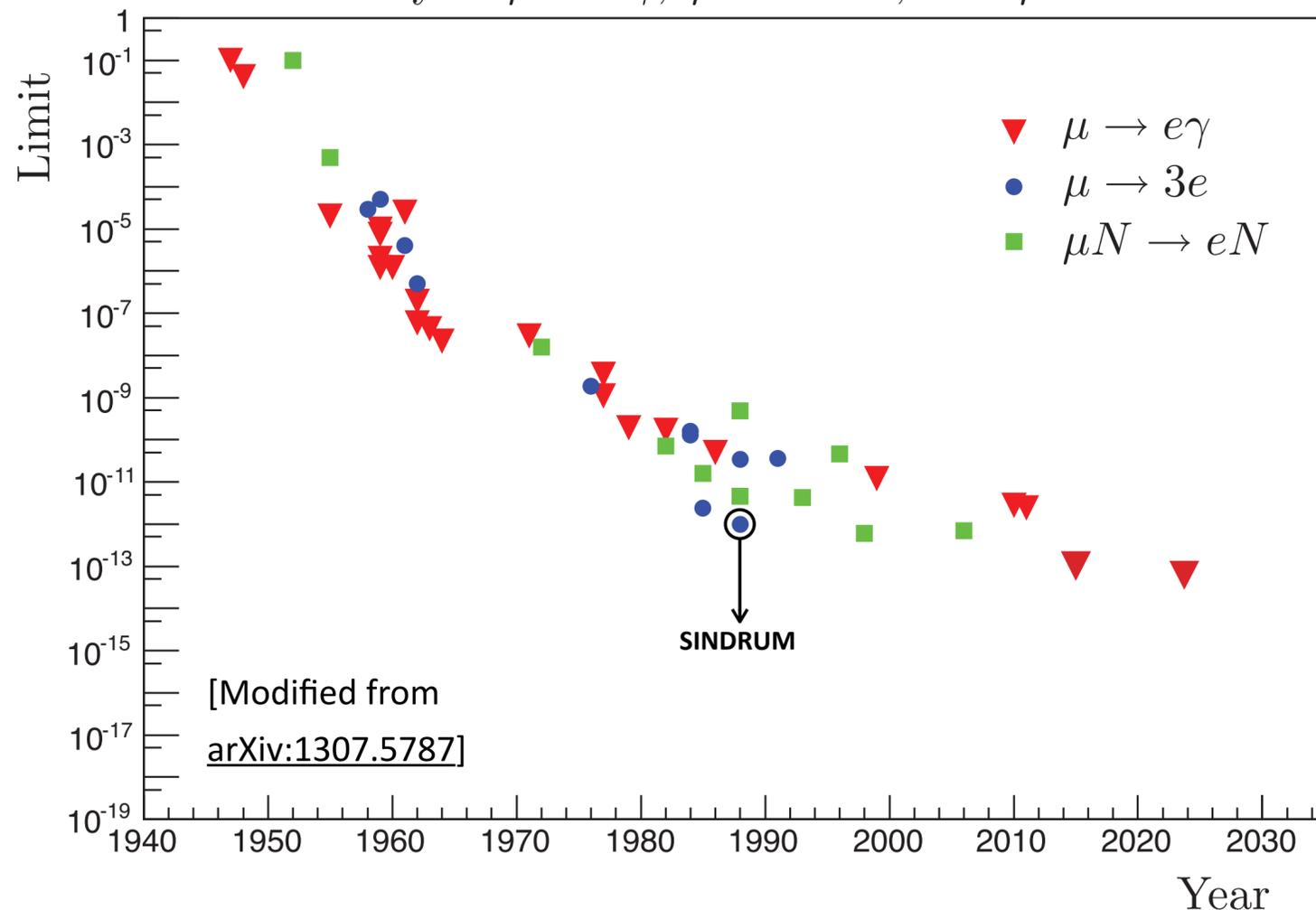
Muon decays ( $\sim 100\%$ ) via:  $\mu \rightarrow e \nu \bar{\nu}$

Highly suppressed BR for charged lepton flavour violating

(cLFV) decays:

$$\Gamma \propto \left( \frac{\Delta m_\nu^2}{m_W^2} \right)^2 \sim \mathcal{O}(10^{-54})$$

History of  $\mu \rightarrow e \gamma$ ,  $\mu N \rightarrow e N$ , and  $\mu \rightarrow 3e$

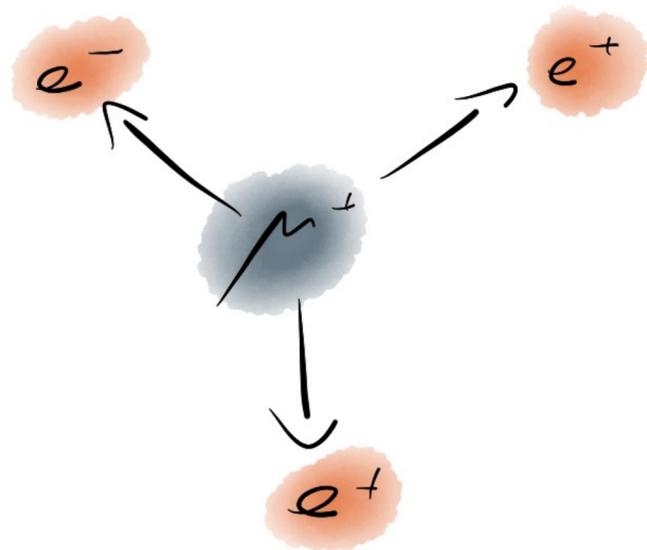


BR( $\mu \rightarrow eee$ )  $< 10^{-12}$  (90% CL) from [[SINDRUM \(1988\)](#)]

- Complementary to other searches (@ LHC, or other muon modes)
- New BSM particles could appear in loop
- *New physics* models involving LFV **significantly enhance the predicted BR, to experimentally measurable levels**

## Signal topology: three electron tracks

- Common vertex
- Time coincidence
- Energy sum =  $m_\mu$
- Decay at rest so  $\sum \vec{p} = 0$

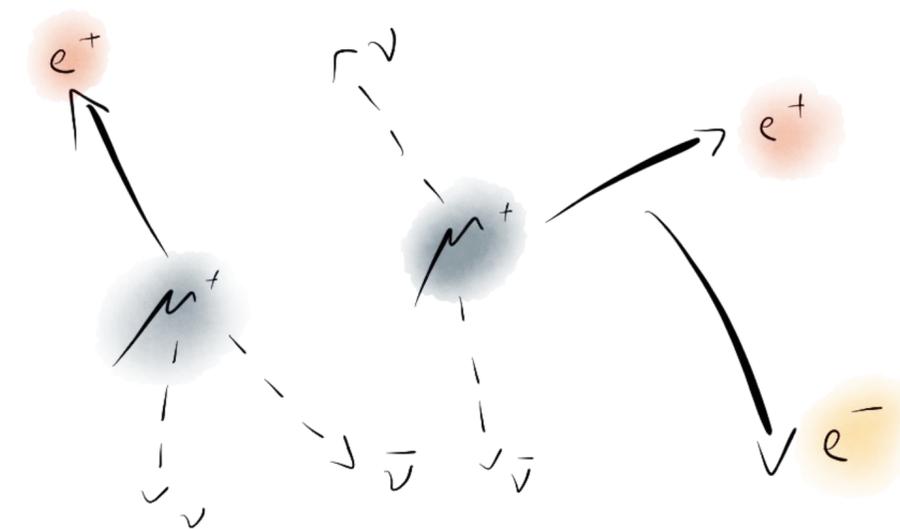


## Main backgrounds:

- Internal conversion (small energy carried away by neutrinos):  
 $BR(\mu \rightarrow eee\nu\nu) = (3.4 \pm 0.4) \times 10^{-5}$

- Accidental: processes appearing to have 3e tracks.

Can occur via: Misreconstruction,  $\gamma$  conversion, Bhabha scattering



## Detector requirements:

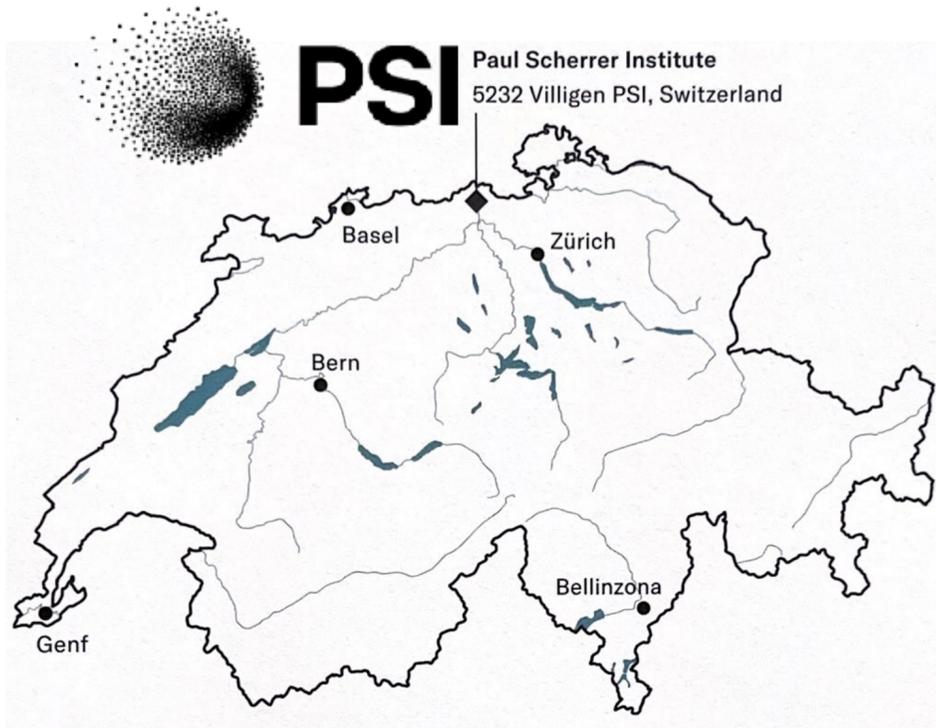
- Tracking in scattering-dominated regime: **low material budget!**
- Good timing and momentum resolution
- Large acceptance to capture electrons

# The Mu3e experiment:

A. McDougall



Located along PIE5 beam-line at the Paul Scherrer Institute ([PSI](#)) near Zurich, CH



Mu3e inside experimental hall

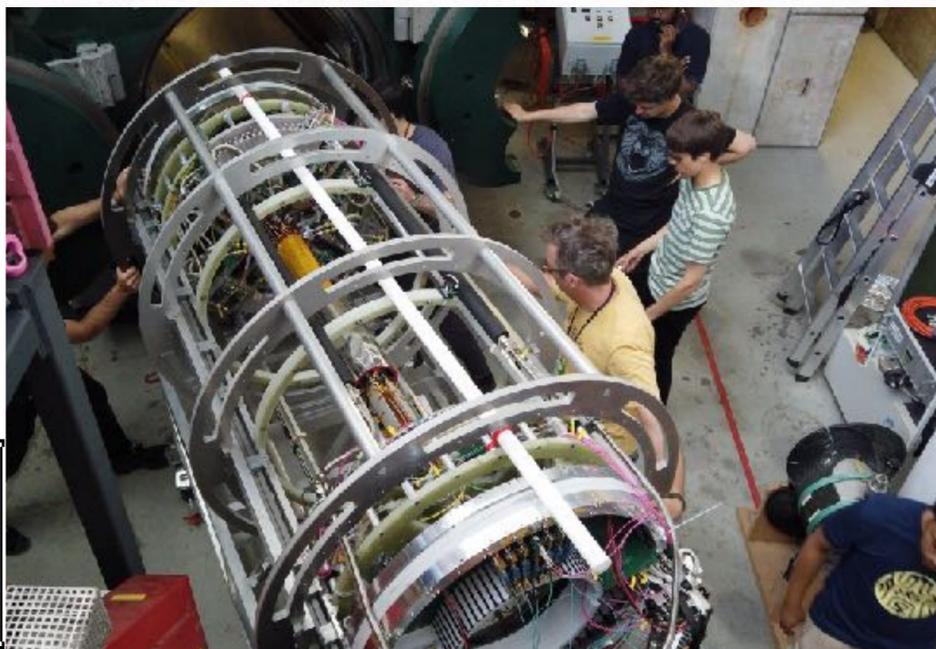
Collaboration  $\mathcal{O}(100)$  people from 11 institutes (DE, UK, CH)

## Expected to start taking physics data in 2026 (Phase I):

- PIE5 provides muon rates up to  **$10^8$  muons/s** to Mu3e
- Target sensitivity:  **$BR(\mu \rightarrow eee) < 2 \cdot 10^{-15}$**
- 290 days minimum running time required to achieve target

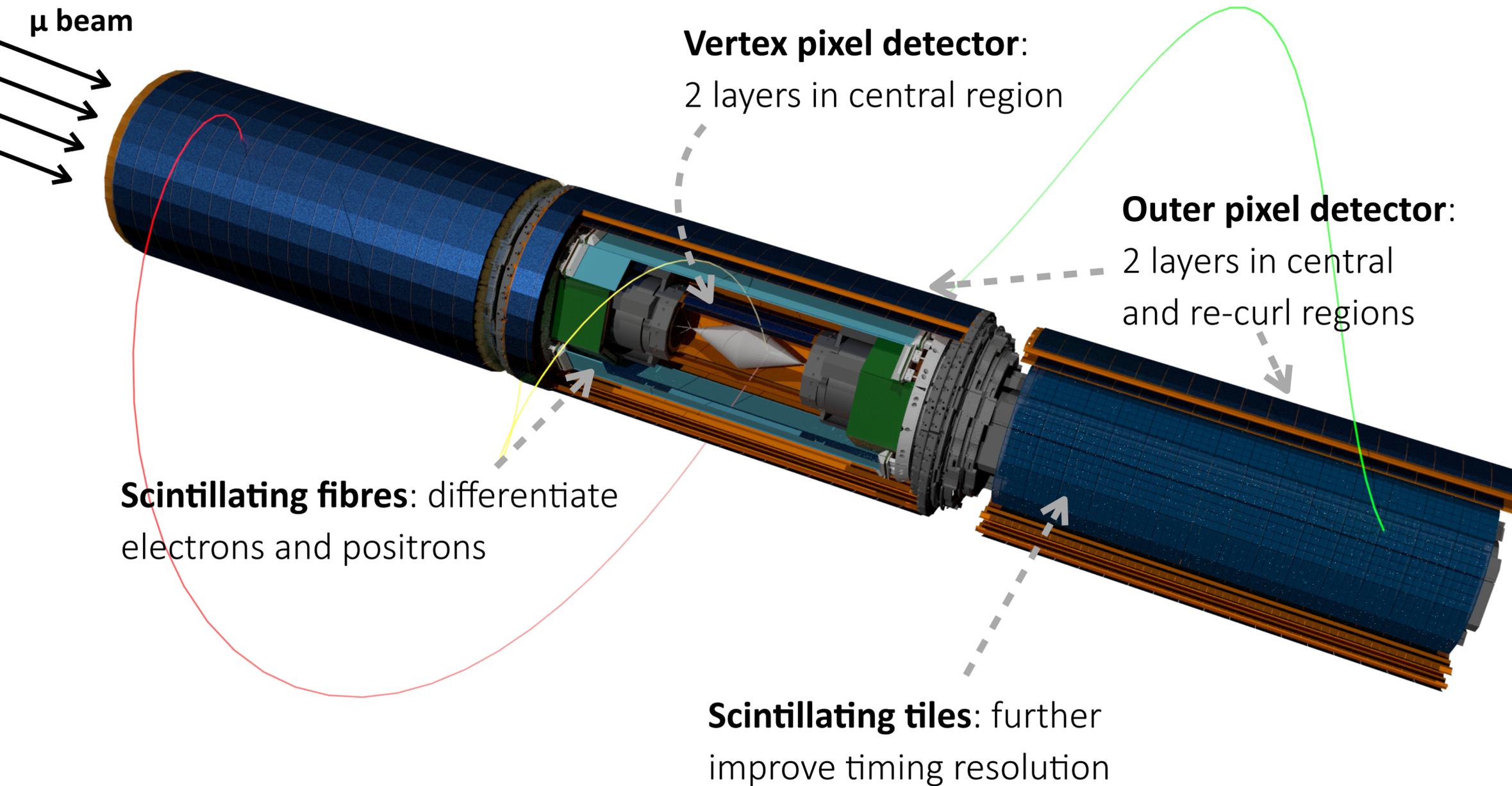
## Phase II (> 2029):

- New High Intensity Muon Beam-line (HIMB), delivering up to  **$10^{10}$  muons/s**
- Target sensitivity:  **$BR(\mu \rightarrow eee) < 2 \cdot 10^{-16}$**



## Detector geometry: **1 central + 2 re-curl regions**

- Homogeneous solenoidal magnetic field  $B = 1\text{T}$
- Multiple scattering dominated: Momentum resolution dependant on number of detector layers and thickness



**Material budget a key factor!**

### Tracking:

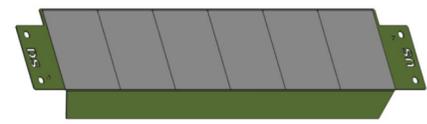
- 50-70  $\mu\text{m}$  thick MuPix11 (Monolithic HV-CMOS) pixel sensors
- Per layer:  $\sim 0.1\%$   $X/X_0$

### Cooling:

- Use gaseous He cooling (less dense compared to air)
- Flow rate 2 - 16 g/s

Basic building block for Mu3e pixel detector: **ladder**

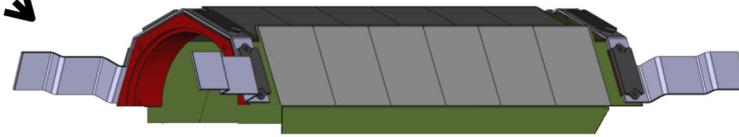
Mechanical stability: primarily from 3D folded nature of vertex detector



**1 ladder = 6 x MuPix11 sensors**



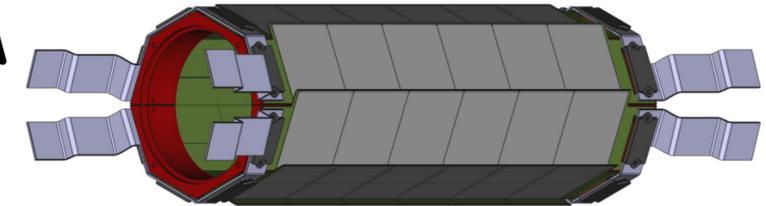
**Ladder**



1 module = 4 ladders



**Module**



2 modules = 1 layer

**Layer**

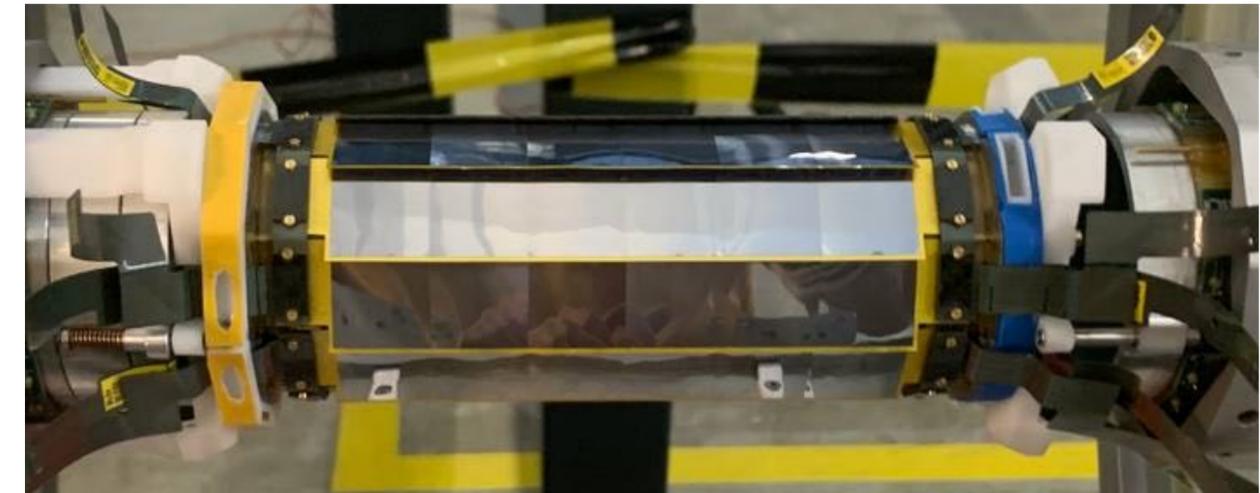
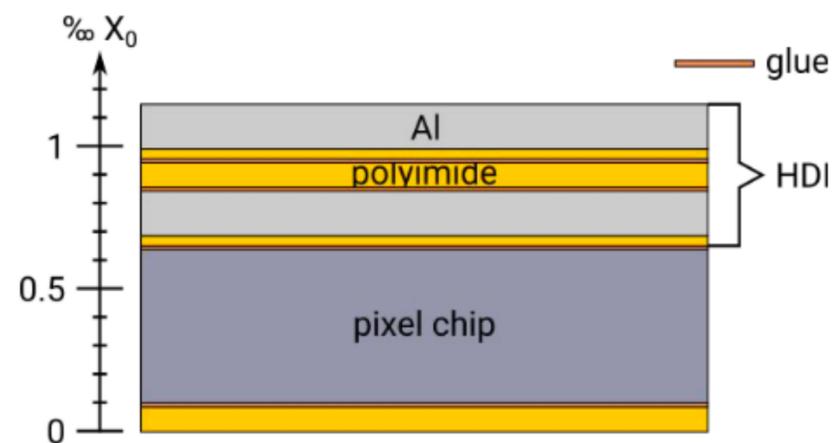
Comprised of:

- 50µm MuPix11 pixel sensors
- Alu/kapton high-density interconnect (HDI)
- 25µm kapton support
- Electrically connected via spTAB connections



spTAB connection:

- Trace width  $\sim 60 \mu\text{m}$
- Pad size  $200 \times 100 \mu\text{m}^2$



Vertex system ("version 1") complete and installed in PIE5 for June 2025 beam-time.

# Outer pixel detector layers:

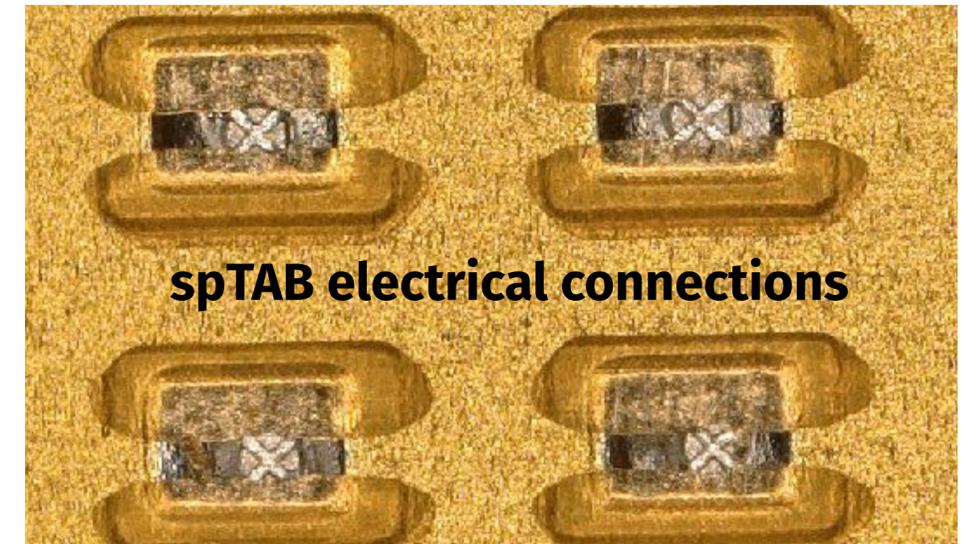
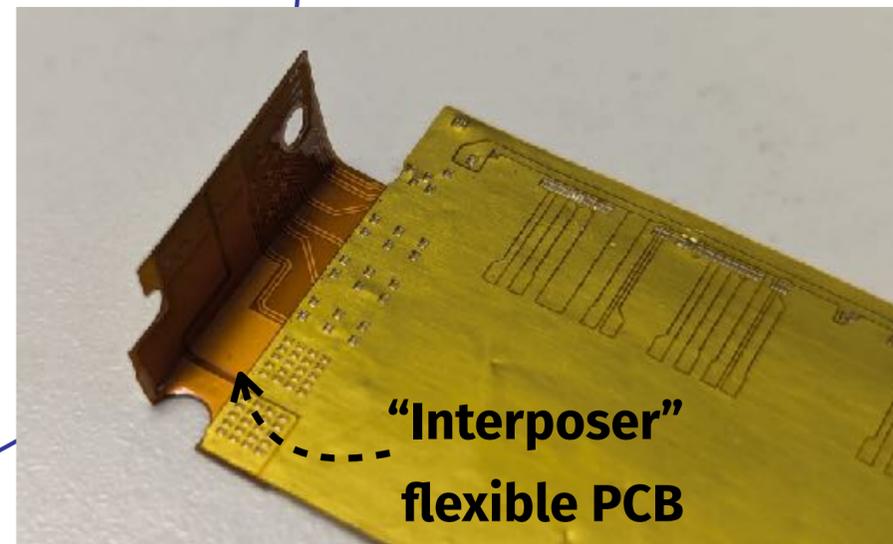
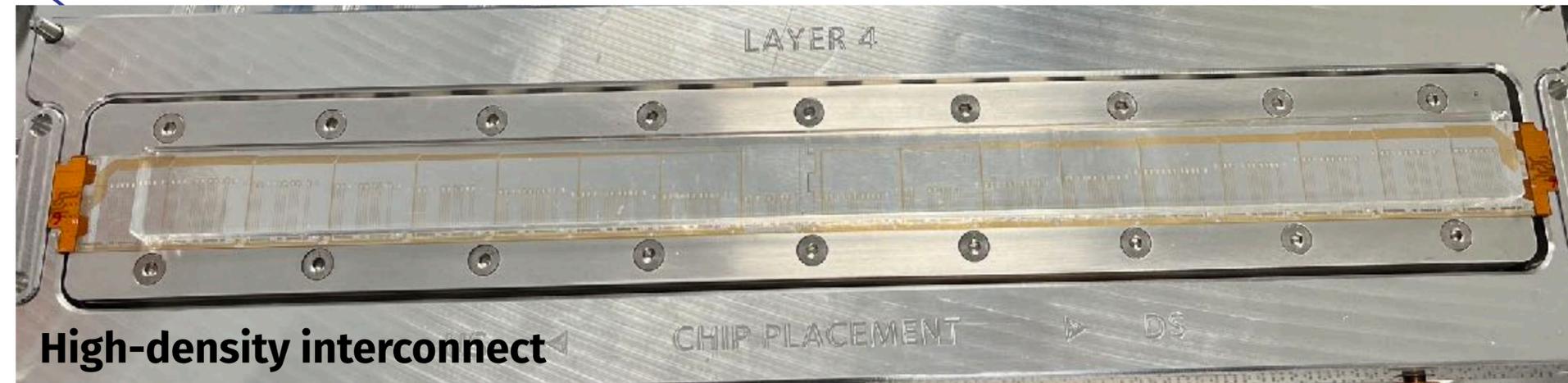
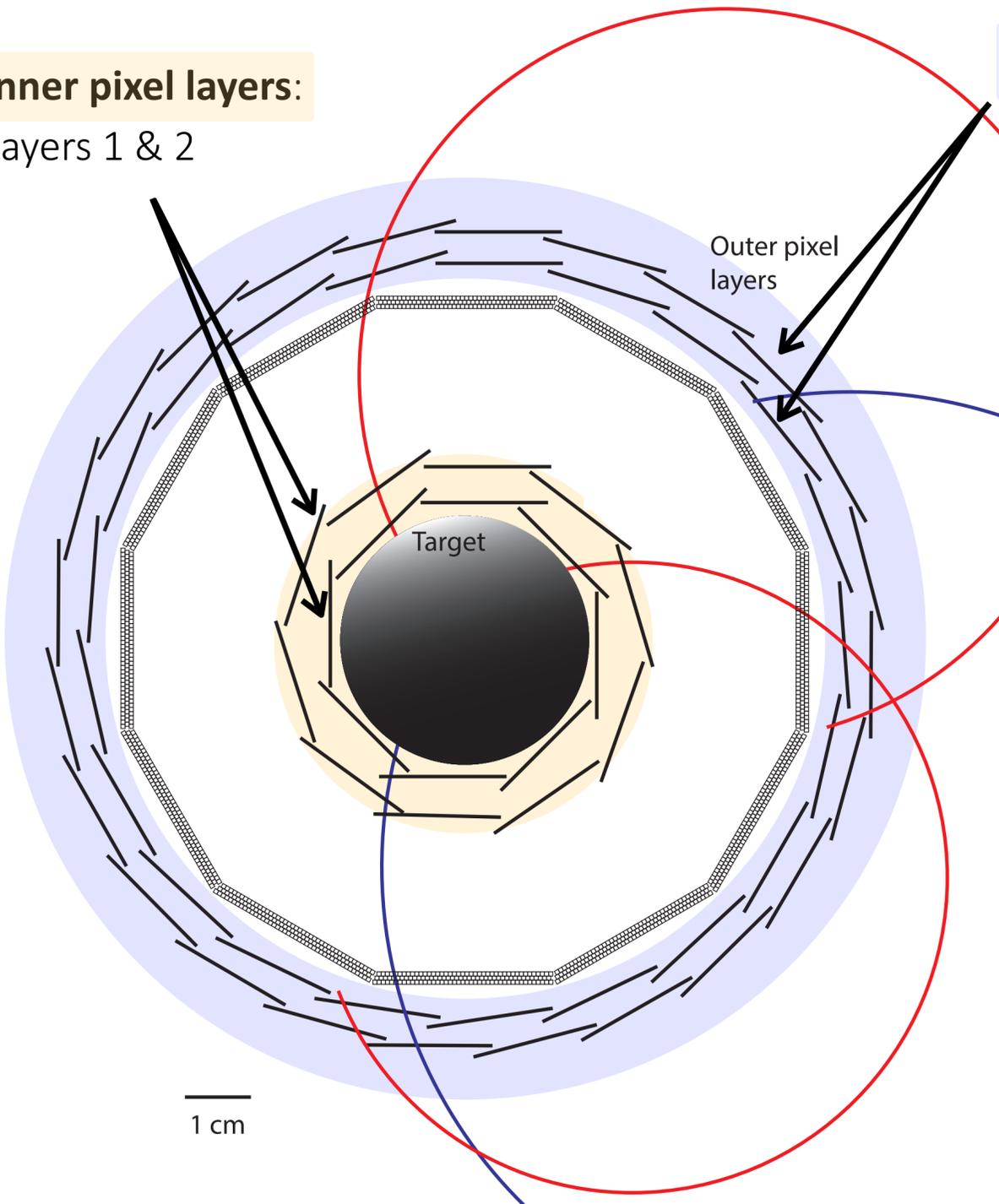
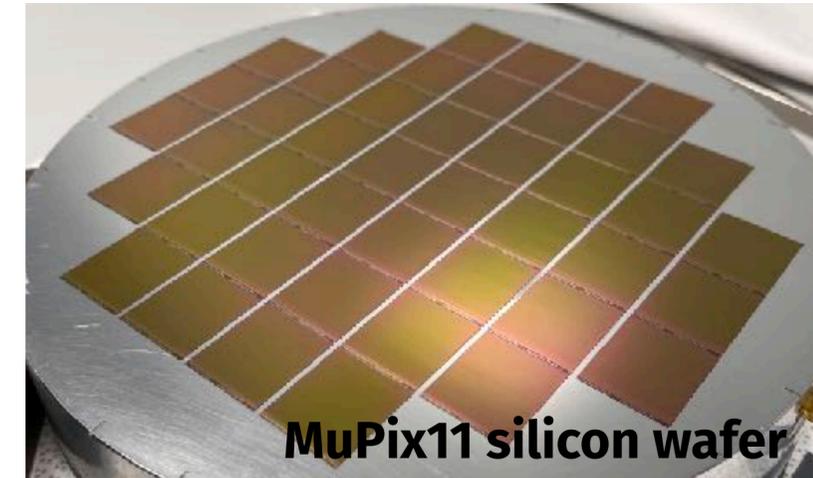
## Inner pixel layers:

Layers 1 & 2

## Outer pixel layers: Layers 3 & 4

Ladders consist of:

- 17-18 70 $\mu$ m MuPix11 pixel sensors
- Alu/kapton high density interconnect (HDI)
- Flexible PCB (“interposer flex”) either end
- Mechanical stiffener for support



Each ladder ~ 2 grams!

Despite it being over 300 mm long ...

Mechanical support provided by either:

## Kapton

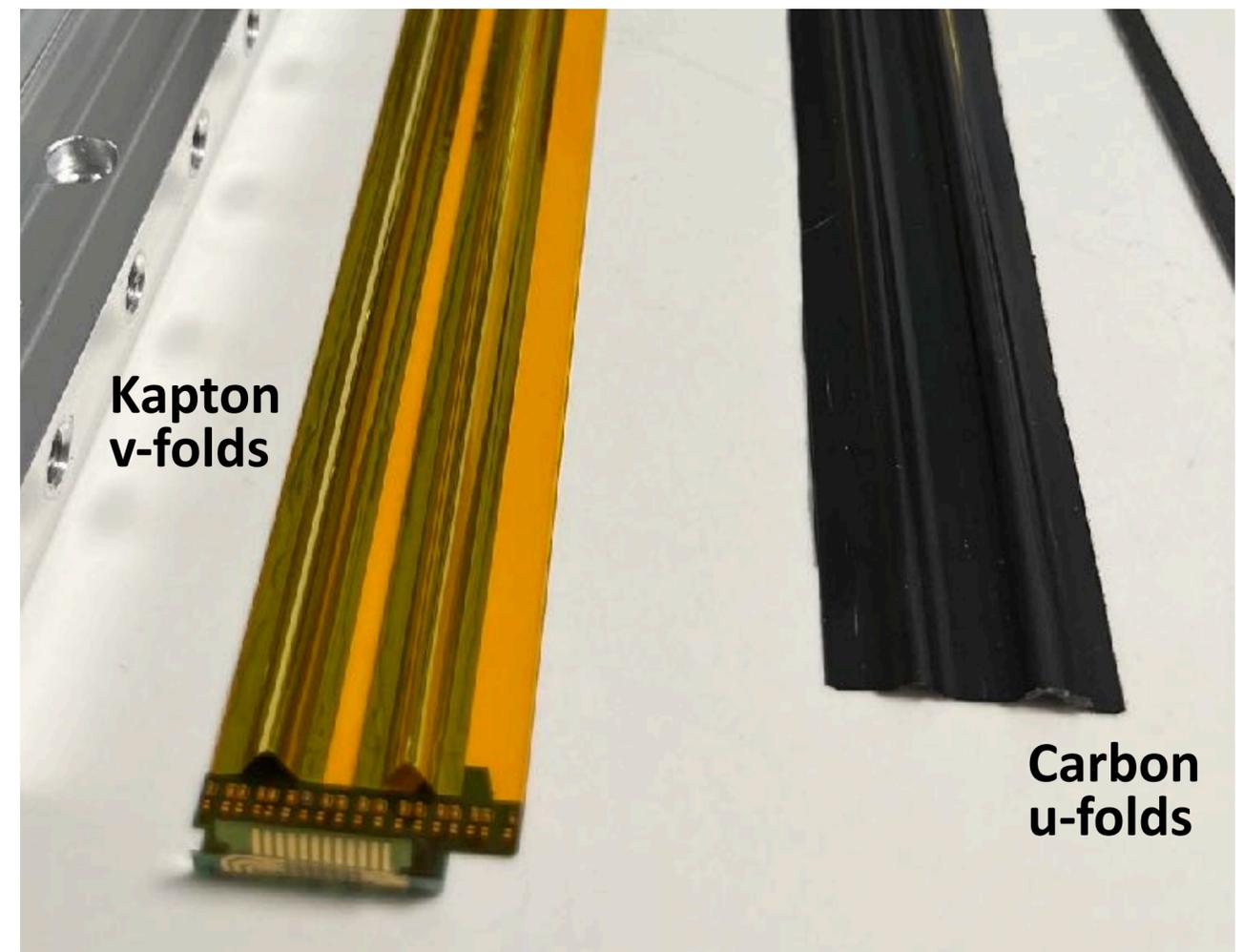
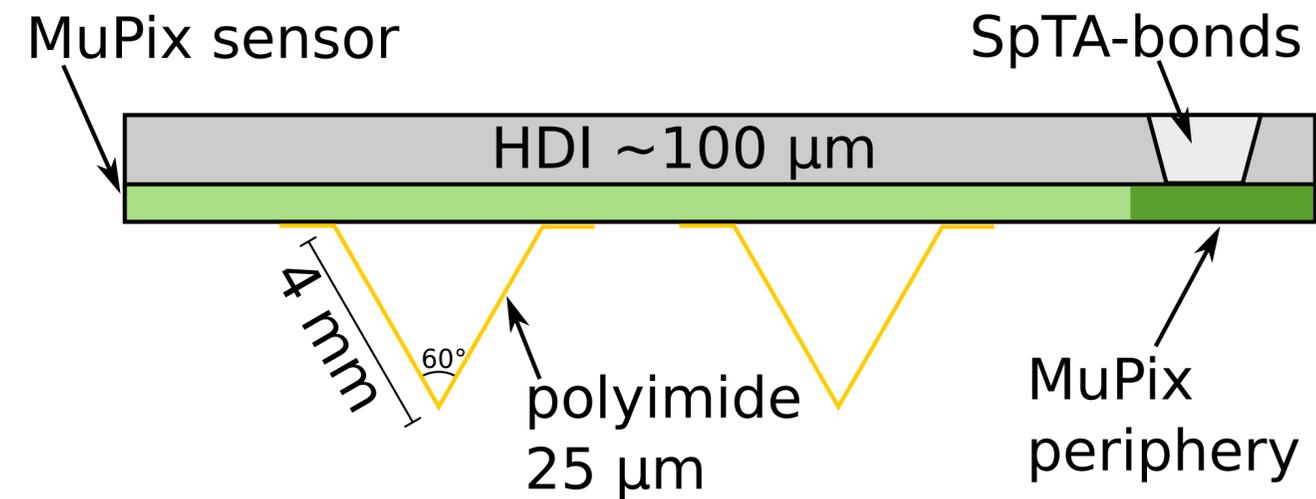
**25 $\mu$ m thick kapton** folded in two triangles, “*v-folds*”:

- Sensors mostly still visible underneath
- Quite delicate  $\rightarrow$  difficulties in transportation
- Seem to provide enough structural integrity for 18 chip ladders, but not more

## Carbon-fibre

**25  $\mu$ m uni-directional carbon-fibre**, with joined “*u-folds*”:

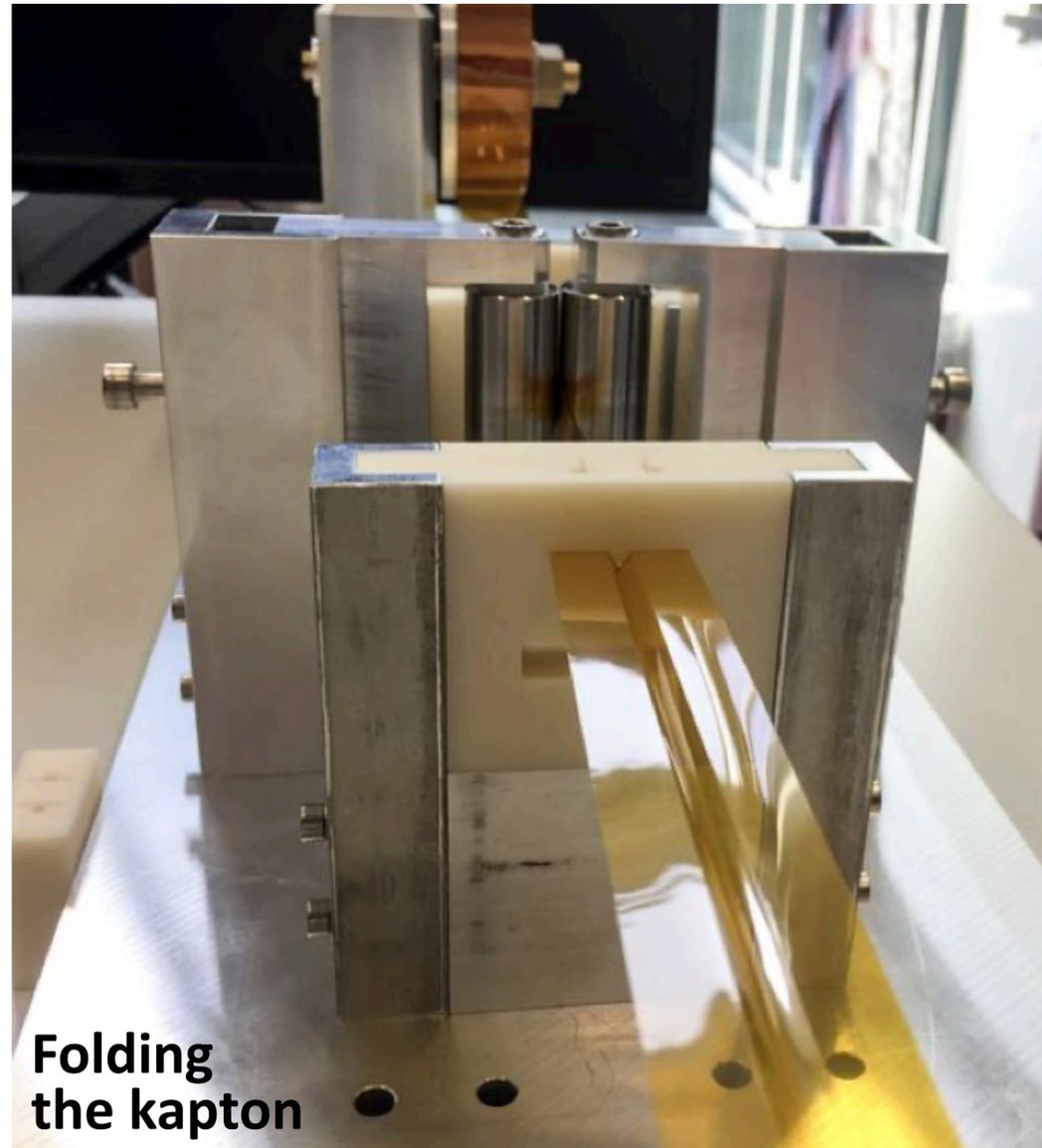
- Moulded into double-u shape
- Co-cured kapton (8 $\mu$ m) backing - electrically separate two halves
- Very stiff along length (impact on yield and transportation)
- Almost entirely covers sensors



**25 $\mu$ m thick kapton sheet** folded in triangular shape: 2 per ladder

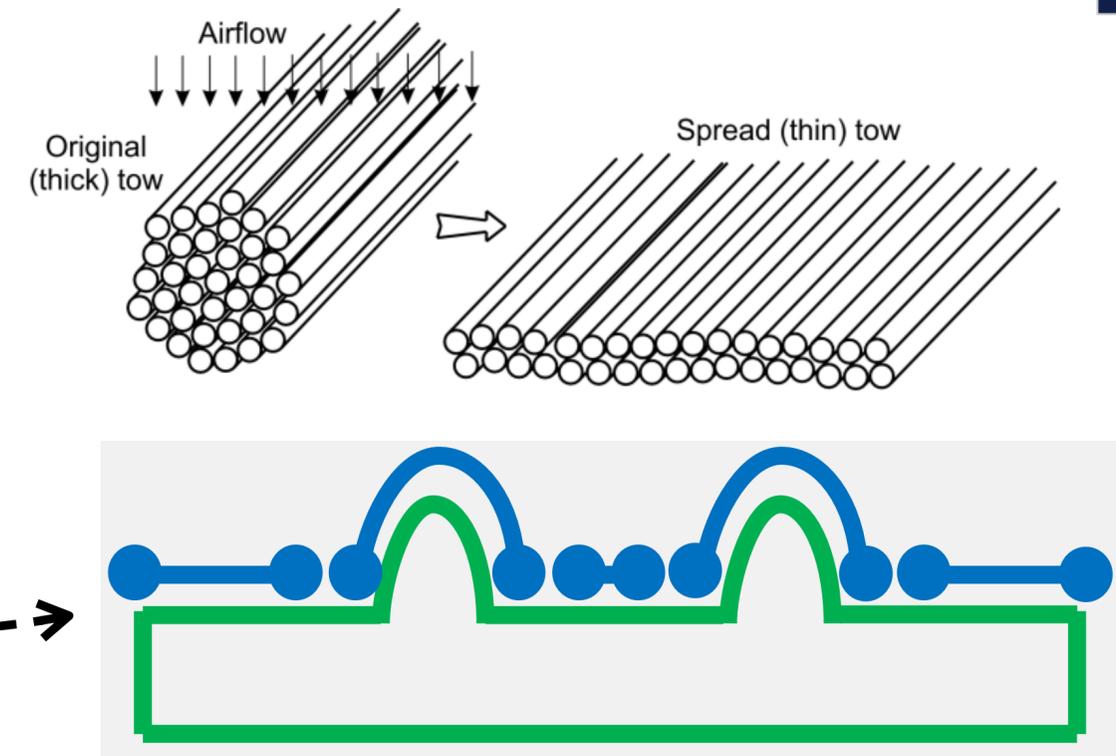
- Thin lines of glue along each of the v-folds
- Folded shape achieved by threading polyimide foil through “folding” machine

**Vacuum to hold the v-folds**



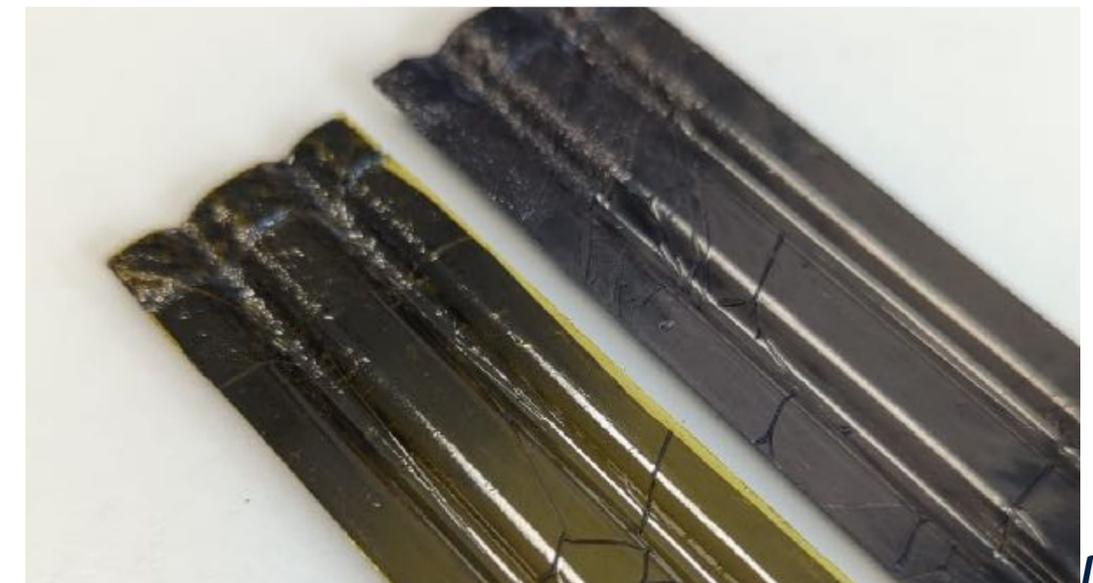
**Uni-directional single-ply 25 $\mu$ m carbon-fibre** sheet (40% resin content):

- **Spread-tow** Tairyfil TC33 fibre and SK Chemicals K51 matrix
  - Material developed for sails for America's cup yacht
  - Usually intended to be woven together
- Split-ply laid together: compliance during warm up/cool down, additional resin to bleed off
- Cured into double "u" shape



Very difficult to work with: 'chaotic' fibre pattern (due to single-ply UD spread tow), bowing issues, handling

- Challenges overcome by Adam Lowe + team through their laminating, tooling and fabrication techniques

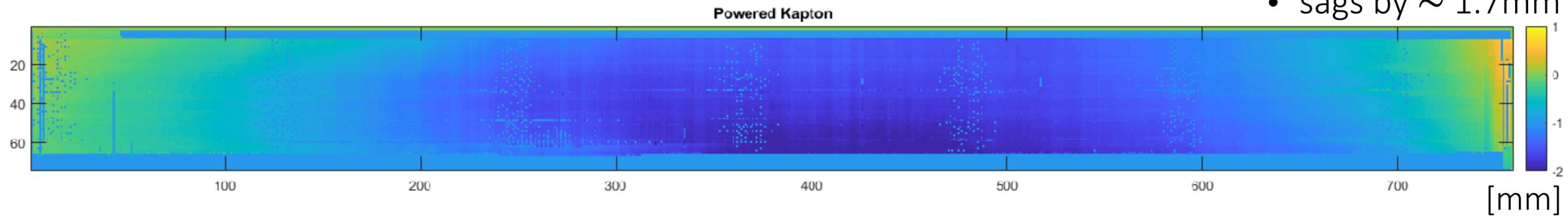


Investigations conducted to compare ladder performance (*using dedicated test objects*):

- Thermally induced out-of-plane deformations
  - Ladders resting freely but supported at either end
  - Neither ladder moved due to heat load

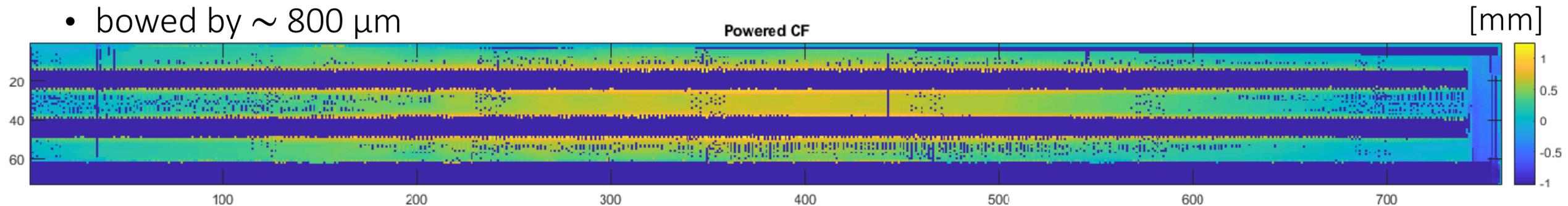
Ladder with **kapton** support:

- sags by  $\sim 1.7\text{mm}$



Ladder with **carbon-fibre** support:

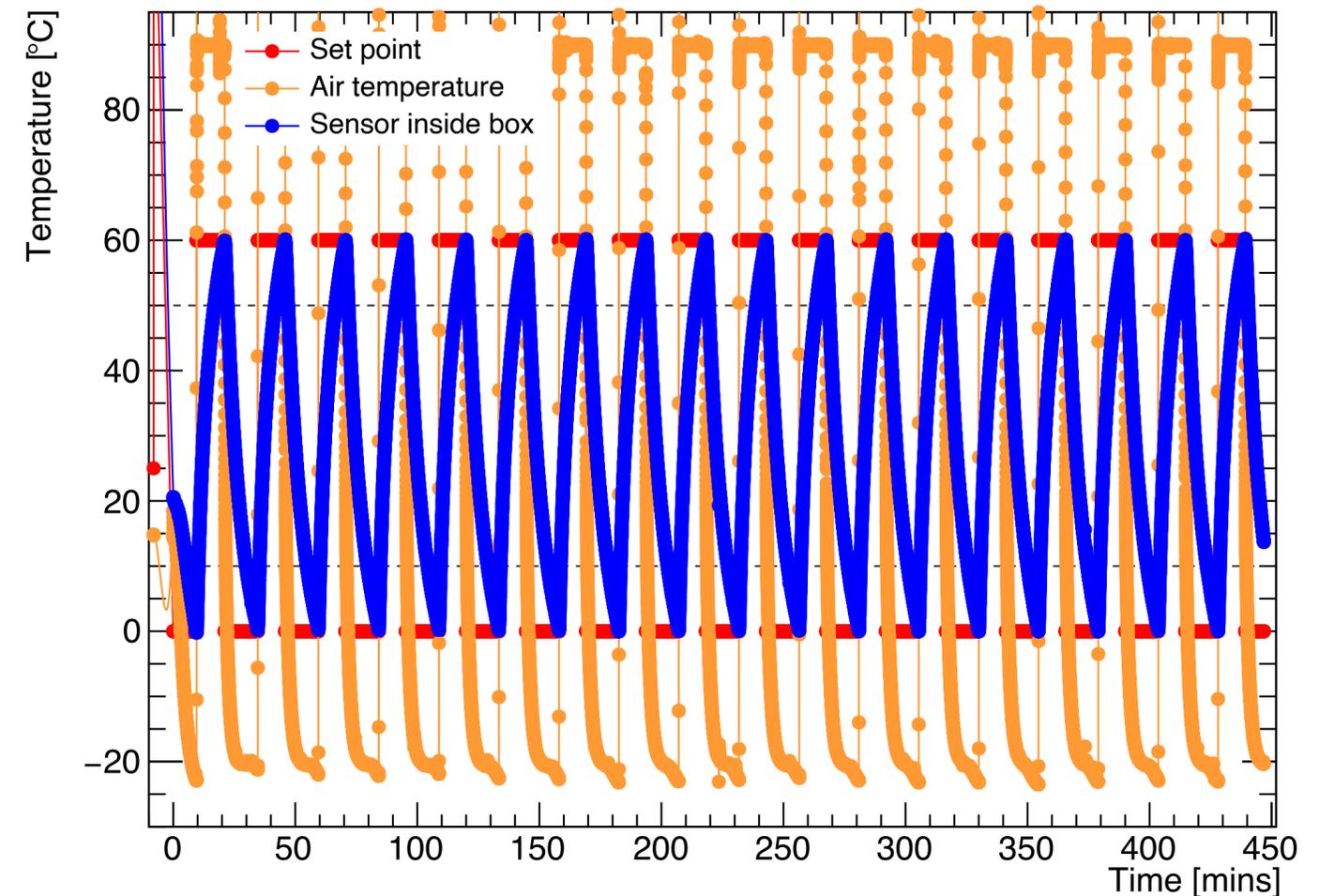
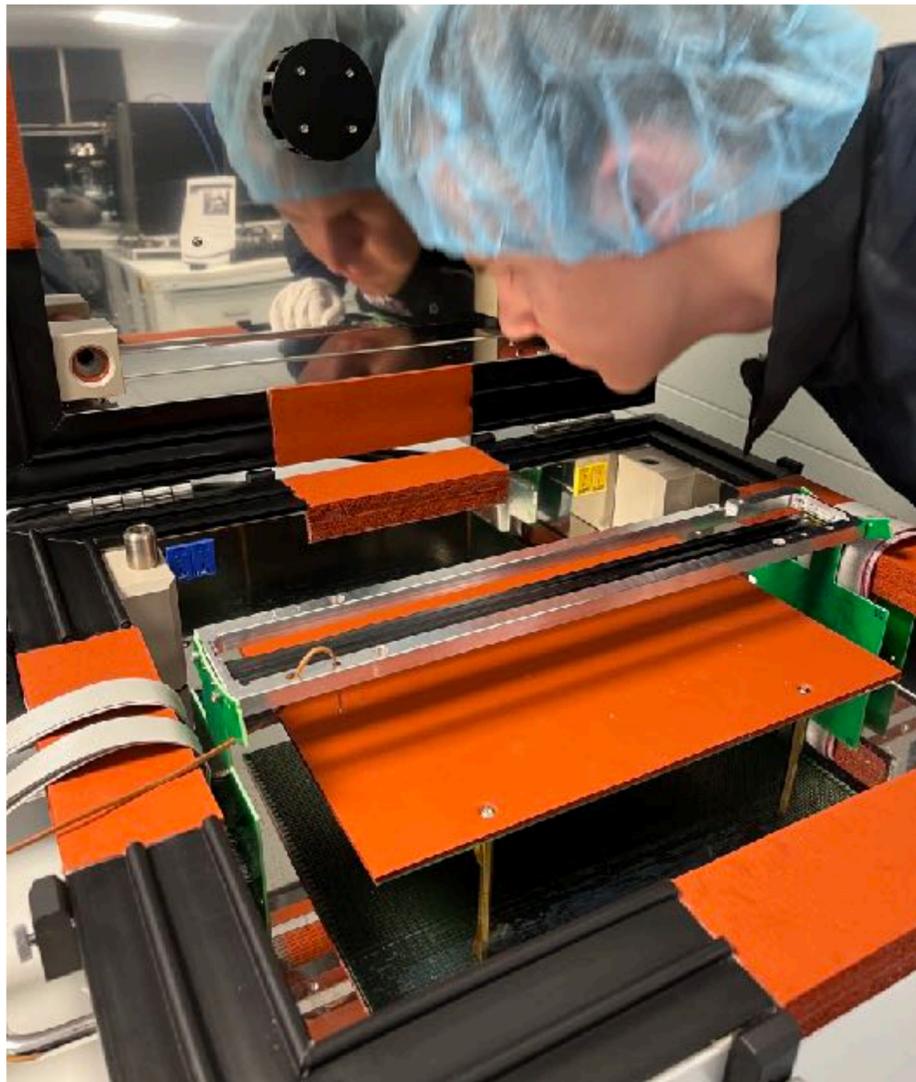
- bowed by  $\sim 800\ \mu\text{m}$



- Temperature uniformity
- Electrical connectivity stability through thermal cycling
- Vibration measurements

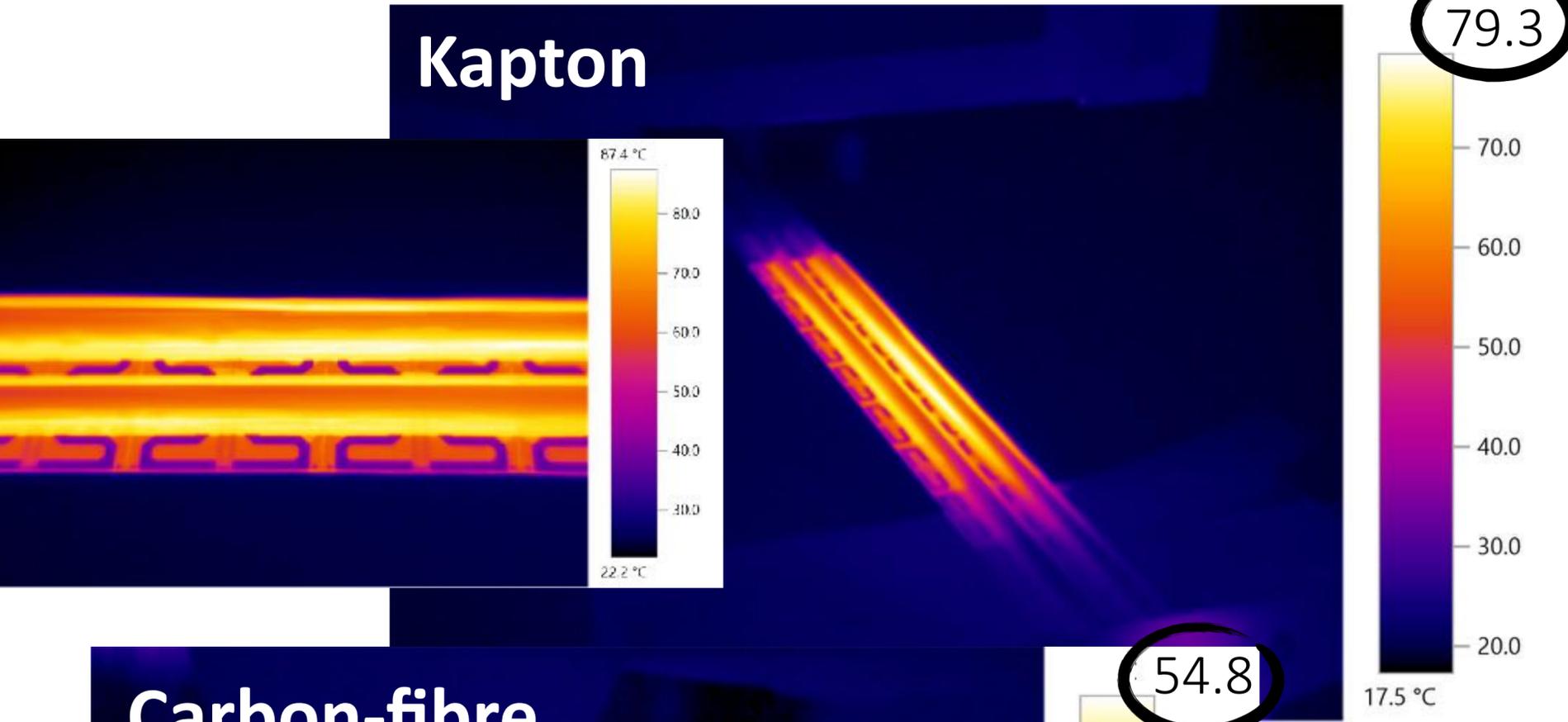
Electrical connectivity tested by thermal cycling (200 times) powered ladders between  $\Delta T = 0 \rightarrow 60^\circ\text{C}$ :

- Large CTE mismatch between Si/kapton and carbon-fibre
- Carbon-fibre ladder general much stiffer --> more stress on Si/HDI



- Kapton ladder: 2 failures seen per  $\sim 50$  cycles
- Carbon-fibre ladder: no failures

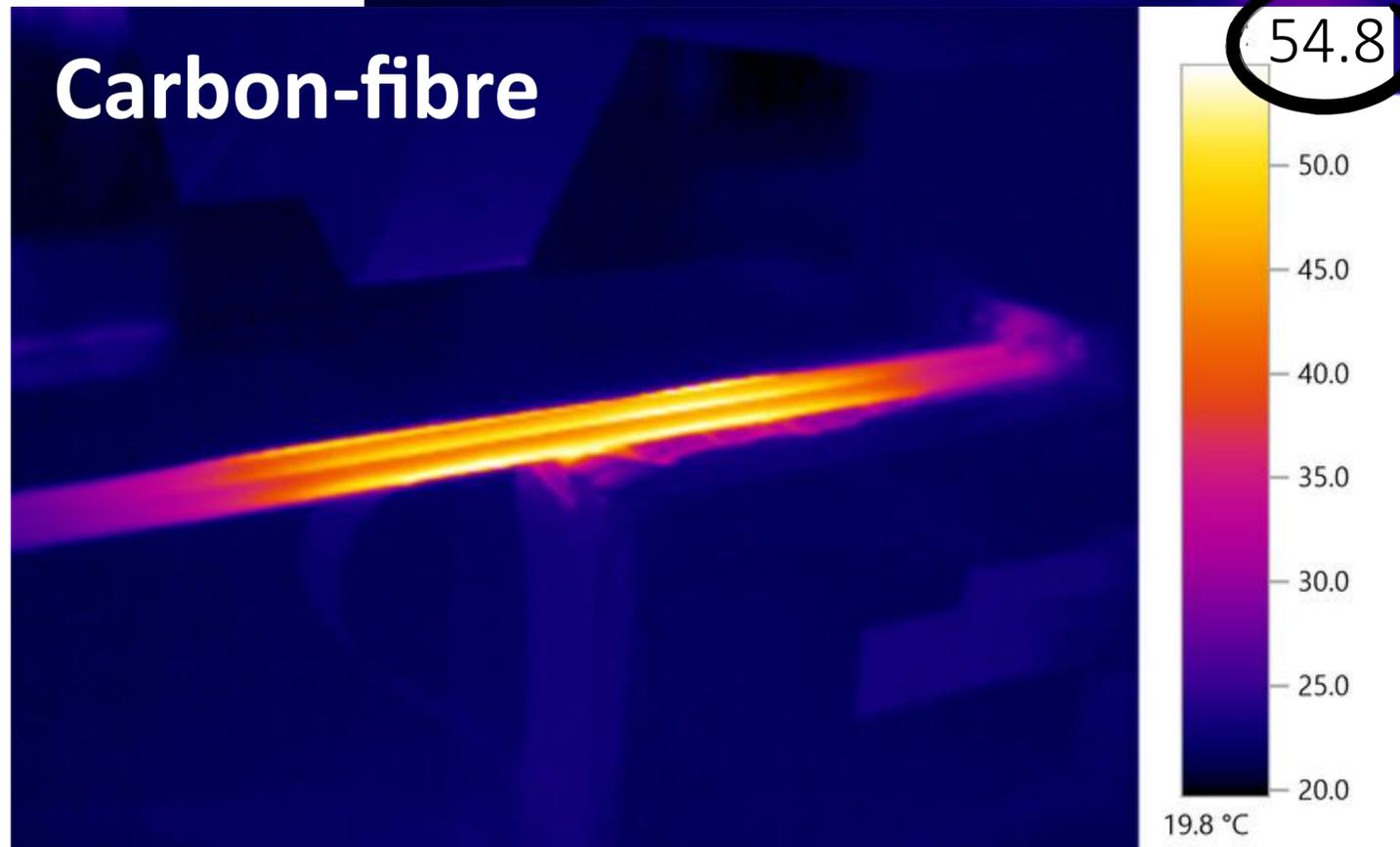
## Kapton



Measure **heat dissipation along ladder** when sensors are powered:

- Carbon-fibre better conductor than kapton: better at dispersing heat along the ladder length
- Carbon ladder reached much lower peak temperatures

## Carbon-fibre



**Vibrations of ladders** due to:

- Tension applied by module supports
- Environment: Helium compressors
- Gaseous flow



**Background Vibrations**  
Equipment & Components produce vibrations at the detector site. This has been measured at PSI. *Mu3e Site Vibrations and smoothing* graph showing Acceleration spectral density (m/s<sup>2</sup>/√Hz) vs Frequency in Hz.

**Track Based Alignment (TBA)**  
TBA methods are effective for correcting static misalignments; however, they struggle to account for dynamic changes that occur on timescales shorter than the algorithm's runtime. The Silicon chips have a thickness of 80µm. *Resolution:*  $\frac{80}{\sqrt{12}} \mu\text{m} \sim 23 \mu\text{m}$ . *Aim:*  $\times 2 \text{ RMS} < 23 \mu\text{m}$ .

**Stiffener and Vibrational Experiment**  
*Proposed material for mechanical stability:* 25µm thick Kapton stiffener vs 25µm thick uni-directional carbon fibre stiffener with 8µm Kapton co-cure. *Set-up:* Shaker Table excites ladder, Displacement measured using capacitive sensors, Acceleration PSD kept constant.

**Ladder Vibration Theory**  
*Response Function/Fit:* Assuming the ladder to be a Harmonic Oscillator one can model the normalised vibrational response as follows:  $|H(f)|^2 = \frac{1}{(1 - (f/f_0)^2)^2 + (f/f_0)^2}$ . In the case of the Bernoulli Beam Model, the vibrational response at a specific position x can be expressed in a similar form:  $|H(f)| = \frac{1}{\sum_n A_n} \sum_n \frac{A_n}{1 - (f/f_n)^2 + i f/f_{nQ}}$ . *Data & Fits:* Graphs showing Measured Data vs HO Model Fit for RMS Displacement (µm) and Normalised RMS Displacement vs Frequency (Hz). *When dividing by A, only f<sub>0</sub> & Q are left. The expression is now unitless.* *Ladder Response Function* graph. *The HO Model has 3 parameters, that fully determine its shape: A, f<sub>0</sub> & Q. Above the fitted x<sub>max</sub>(f) is shown for a carbon fibre ladder.*

## Entire ladder production for the outer pixel tracker in Oxford cleanroom

### Ladder → module → layer:

- 17 (18) x MuPix11 sensors in layer 3 (4)
- 4 ladders per module
- 6 (7) modules in layer 3 (4)

**Total per station: 52 ladders** (912 sensors)

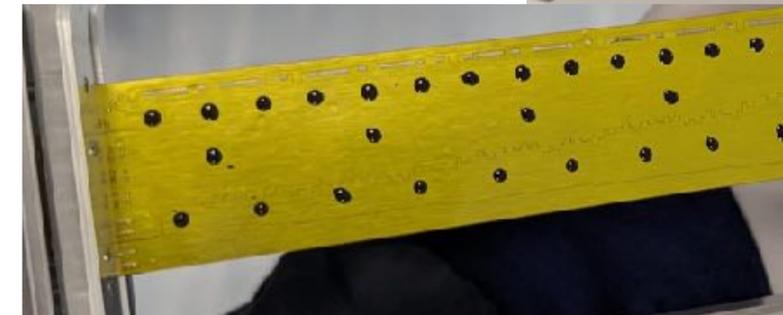
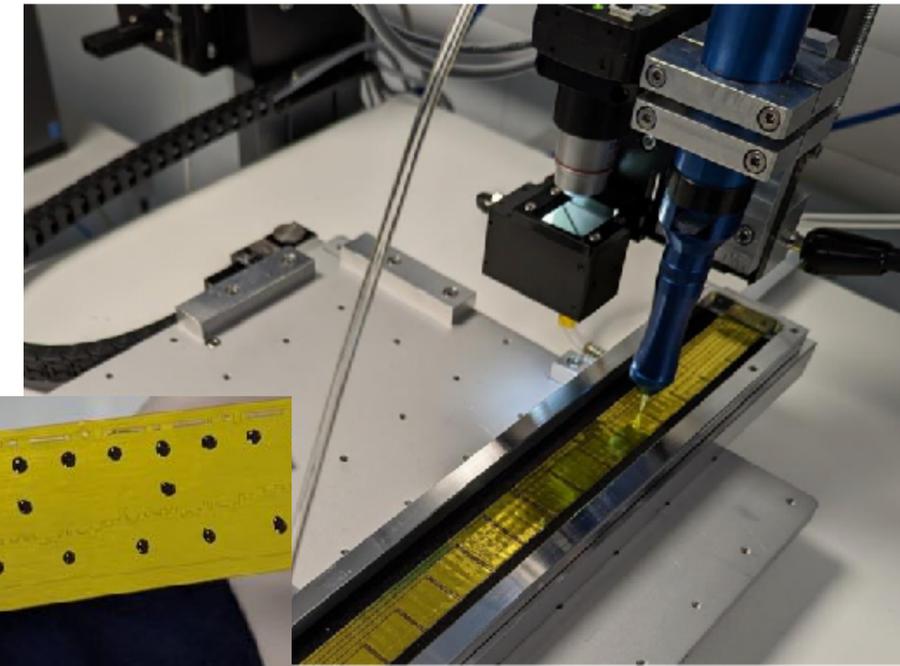
Automate ladder building procedure as much as possible:

- Robotic gantry used for placement of chips



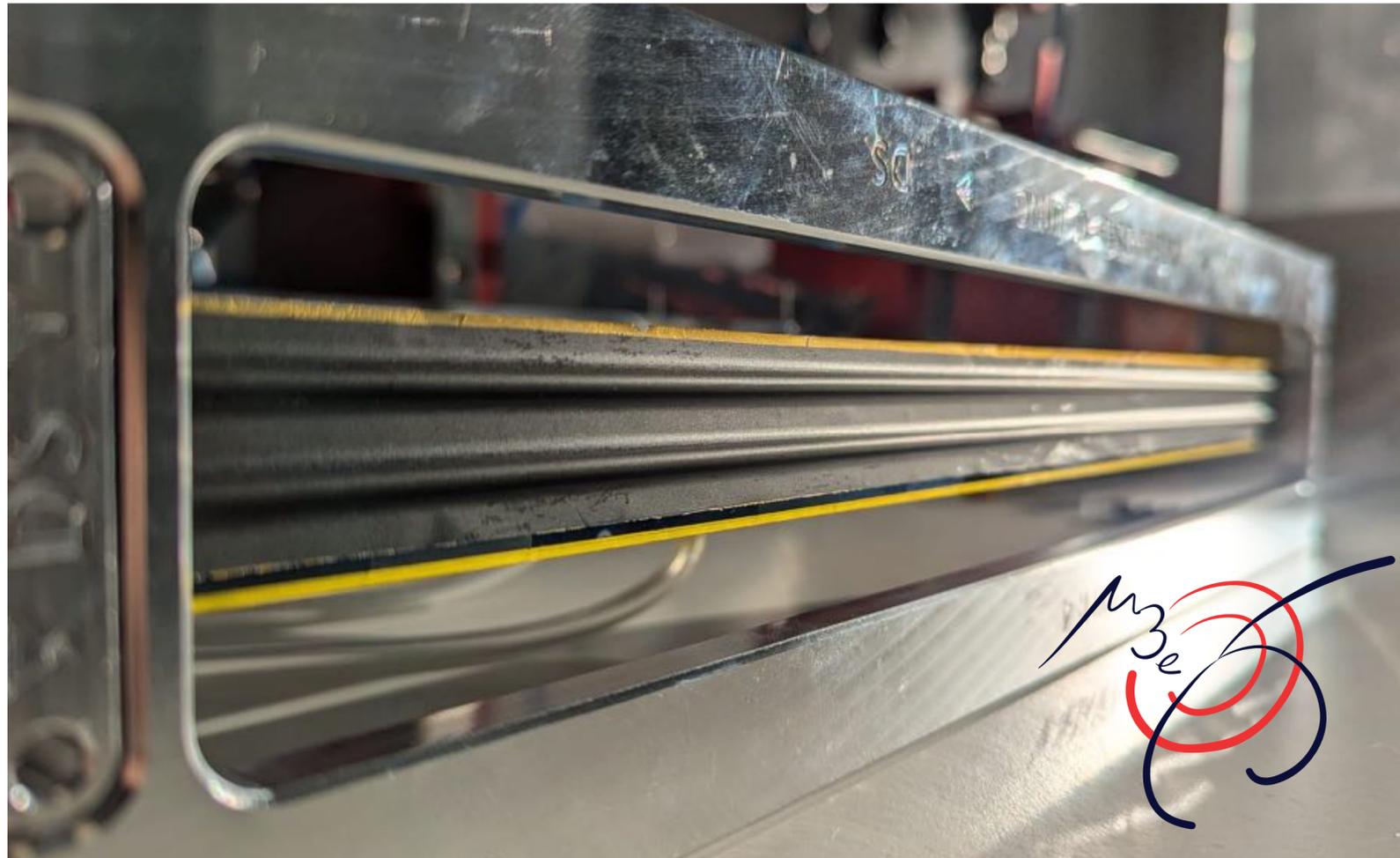
Glue-dispensing robot:

- Allows for precise placement and size of glue deposits



- Carbon-fibre stiffener vacuum held via suction cups:





## **Mu3e on the cutting edge of ultra light-weight pixel tracking detectors!**

Investigations into choice of stiffener material for the longer outer pixel ladders: **kapton vs. carbon-fibre**

- Carbon-fibre demonstrates favourable properties: thermally, stiffness, handleability

Production of outer pixel ladders on-going.

**Expect physics data-taking to commence in 2026!**

*Stay tuned ... !*

[[Mu3e collaboration](#)]

[[Oxford silicon detector group](#)]

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